

Amendments to the Claims

The following listing of claims will replace all prior versions of claims in the application.

1.-12. (cancelled)

13. (Currently Amended) A method of sealing chip-type devices, comprising the steps of:

1) providing an adhesive composition which exhibits a minimum value of a storage modulus of elasticity before curing from 1×10^3 to 5×10^5 Pa measured by using a dynamic visco-elasticity measuring apparatus while elevating the temperature from 80°C to 150°C at an elevating temperature rate of 2.4°C/min and at a shearing rate of 6.28 rad/sec and a storage modulus of elasticity after curing from 5×10^5 to 5×10^7 Pa measured by using a dynamic visco-elasticity measuring apparatus at a sample temperature of 150°C in a tensile mode at a measuring frequency of 6.28 rad/sec;

2) arranging a layer of the adhesive composition as an adhesive layer of a film adhesive for sealing or a film laminate for sealing of claim 1 to be contacted with the upper surfaces of a plurality of chip-type devices on a substrate having said plurality of chip-type devices; and

3) heating and press-adhering said film adhesive or laminate, and curing the film adhesive to seal said plurality of chip-type devices at one time.

14. (original) A sealing method according to claim 13, further comprising a step of singulating after said plurality of chip-type devices have been sealed.

15. (new) The sealing method of claim 13, wherein said adhesive layer includes a plurality of layers, and the outermost layer of said layers, which is in contact with the chip-type devices has a storage modulus of elasticity before curing that is higher than those of the inner layers.

16. (new) The sealing method of claim 15, wherein the outermost layer has a storage modulus of elasticity before curing that is higher than that of the innermost layer by at least 0.2×10^3 Pa.

17. (new) The sealing method of claim 13, wherein the adhesive composition used for said adhesive layer is a reactive hot-melt adhesive composition comprising a thermosetting resin component and a thermoplastic resin component.

18. (new) The sealing method of claim 17, wherein the reactive hot-melt adhesive composition comprises a mixture of a polymer comprising a vinyl group-containing monomeric unit and a polymer comprising an epoxy group-containing monomeric unit, or a copolymer comprising vinyl group-containing monomeric unit and an epoxy group-containing monomeric unit.

19. (new) The sealing method of claim 17, wherein a fluidity of the reactive hot-melt adhesive composition is controlled by incorporation of a cross-linking structure in the polymer compound.

20. (new) The sealing method of claim 19, wherein the polymer or copolymer of the reactive hot-melt adhesive composition is cross-linked by an electron beam.

21. (new) The sealing method of claim 17, wherein the reactive hot-melt adhesive composition is one in which a precursor comprising a photo-cationic polymerization catalyst is photo-polymerized with the polymer or copolymer.

22. (new) The sealing method of claim 19, wherein said photo-polymerization is effected by irradiation of ultraviolet ray.

23. (new) The sealing method of claim 17, wherein the reactive hot-melt adhesive composition further comprises a rosin.

24. (new) The sealing method of claim 23, wherein the adhesive composition comprises from 10 to 95% by mass of a thermosetting resin, from 4 to 80% by mass of a thermoplastic resin, and from 1 to 20% by mass of a rosin.